



Material Content Data Sheet



Halogen-Free

Sales Product Name	BFP 843 H6327	Issued	11. May 2021
MA#	MA001666944		
Package	PG-SOT343-4-2	Weight*	6.93 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.001	0.01		101	
	noble metal	gold	7440-57-5	0.003	0.04		394	
	inorganic material	silicon	7440-21-3	0.024	0.35	0.40	3465	3960
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		100	
	non noble metal	titanium	7440-32-6	0.003	0.05		498	
	non noble metal	chromium	7440-47-3	0.010	0.15		1493	
	non noble metal	copper	7440-50-8	3.433	49.54	49.75	495588	497679
wire	noble metal	gold	7440-57-5	0.009	0.13	0.13	1265	1265
encapsulation	organic material	carbon black	1333-86-4	0.030	0.44		4371	
	plastics	epoxy resin	-	0.651	9.40		93980	
	inorganic material	silicondioxide	60676-86-0	2.347	33.88	43.72	338766	437117
leadfinish	non noble metal	tin	7440-31-5	0.199	2.88	2.88	28760	28760
plating	noble metal	silver	7440-22-4	0.216	3.12	3.12	31219	31219
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com